

June 2009

# FDV301N Digital FET, N-Channel

### **General Description**

This N-Channel logic level enhancement mode field effect transistor is produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance. This device has been designed especially for low voltage applications as a replacement for digital transistors. Since bias resistors are not required, this one N-channel FET can replace several different digital transistors, with different bias resistor values.

#### **Features**

■ 25 V, 0.22 A continuous, 0.5 A Peak.

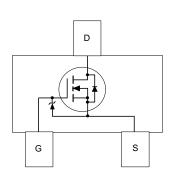
$$\begin{split} R_{\text{DS(ON)}} &= 5~\Omega~@~\text{V}_{\text{GS}} \text{= 2.7 V} \\ R_{\text{DS(ON)}} &= 4~\Omega~@~\text{V}_{\text{GS}} \text{= 4.5 V}. \end{split}$$

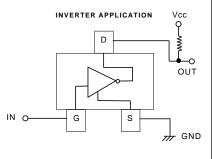
- Very low level gate drive requirements allowing direct operation in 3V circuits. V<sub>GS(th)</sub> < 1.06V.
- Gate-Source Zener for ESD ruggedness. >6kV Human Body Model
- Replace multiple NPN digital transistors with one DMOS



Mark:301







# **Absolute Maximum Ratings** $T_A = 25^{\circ}C$ unless other wise noted

Symbol	Parameter	FDV301N	
Cyllibol	1 diameter	1 5 7 30 114	Units
$V_{\rm DSS}$ , $V_{\rm CC}$	Drain-Source Voltage, Power Supply Voltage	25	V
$V_{GSS}$ , $V_{I}$	Gate-Source Voltage, V <sub>IN</sub>	8	V
I <sub>D</sub> , I <sub>O</sub>	Drain/Output Current - Continuous	0.22	А
		0.5	
P <sub>D</sub>	Maximum Power Dissipation	0.35	W
T <sub>J</sub> ,T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to 150	℃
ESD Electrostatic Discharge Rating MIL-STD-883D Human Body Model (100pf / 1500 Ohm)		6.0	kV
THERMAI	CHARACTERISTICS		
R <sub>gJA</sub> Thermal Resistance, Junction-to-Ambient		357	°C/W

Inverter Electrical Characteristics (T <sub>A</sub> = 25 °C unless otherwise noted)						
Symbol	Parameter	Conditions	Min	Тур	Max	Units
I <sub>O (off)</sub>	Zero Input Voltage Output Current	$V_{CC} = 20 \text{ V}, \ V_{I} = 0 \text{ V}$			1	μA
V <sub>I (off)</sub>	Input Voltage	$V_{CC} = 5 \text{ V}, I_{O} = 10 \mu\text{A}$			0.5	V
V <sub>I (on)</sub>		$V_0 = 0.3 \text{ V}, I_0 = 0.005 \text{ A}$	1			V
R <sub>o (on)</sub>	Output to Ground Resistance	$V_1 = 2.7 \text{ V}, \ I_0 = 0.2 \text{ A}$		4	5	Ω

# **Electrical Characteristics** ( $T_A = 25$ $^{\circ}$ C unless otherwise noted )

Symbol	Parameter	Conditions		Min	Тур	Max	Units
OFF CHARA	ACTERISTICS						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		25			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to 2	5°C		25		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 20 \text{ V}, \ V_{GS} = 0 \text{ V}$				1	μΑ
			T <sub>J</sub> = 55°C			10	μA
I <sub>GSS</sub>	Gate - Body Leakage Current	$V_{GS} = 8 \text{ V}, \ V_{DS} = 0 \text{ V}$				100	nA
ON CHARAC	TERISTICS (Note)	·					
$\Delta V_{GS(th)}/\Delta T_{J}$	Gate Threshold Voltage Temp. Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to 2	5°C		-2.1		mV/°C
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		0.70	0.85	1.06	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 2.7 \text{ V}, I_D = 0.2 \text{ A}$			3.8	5	Ω
			T <sub>J</sub> =125°C		6.3	9	
		$V_{GS} = 4.5 \text{ V}, I_D = 0.4 \text{ A}$			3.1	4	
I <sub>D(ON)</sub>	On-State Drain Current	$V_{GS} = 2.7 \text{ V}, \ V_{DS} = 5 \text{ V}$		0.2			Α
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 0.4 \text{ A}$			0.2		S
DYNAMIC CH	HARACTERISTICS	·					
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			9.5		pF
C <sub>oss</sub>	Output Capacitance				6		pF
C <sub>rss</sub>	Reverse Transfer Capacitance				1.3		pF
SWITCHING	CHARACTERISTICS (Note)						
t <sub>D(on)</sub>	Turn - On Delay Time	$V_{DD} = 6 \text{ V}, I_{D} = 0.5 \text{ A},$			3.2	8	ns
t,	Turn - On Rise Time	$V_{GS} = 4.5 \text{ V}, R_{GEN} = 50 \Omega$	$V_{GS} = 4.5 \text{ V}, R_{GEN} = 50 \Omega$		6	15	ns
t <sub>D(off)</sub>	Turn - Off Delay Time				3.5	8	ns
t <sub>f</sub>	Turn - Off Fall Time				3.5	8	ns
$Q_g$	Total Gate Charge	$V_{DS} = 5 \text{ V}, I_{D} = 0.2 \text{ A},$ $V_{GS} = 4.5 \text{ V}$			0.49	0.7	nC
$Q_{gs}$	Gate-Source Charge				0.22		nC
$Q_{gd}$	Gate-Drain Charge				0.07		nC
DRAIN-SOUP	RCE DIODE CHARACTERISTICS AND MAXIMU	JM RATINGS					
Is	Maximum Continuous Drain-Source Diode For	rward Current				0.29	А
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 0.29 \text{ A}$ (Note)			0.8	1.2	V
	1	•					

Note:
Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2.0%.

# **Typical Electrical Characteristics**

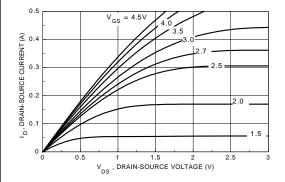


Figure 1. On-Region Characteristics.

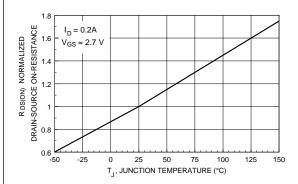


Figure 3. On-Resistance Variation with Temperature.

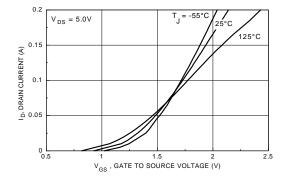


Figure 5. Transfer Characteristics.

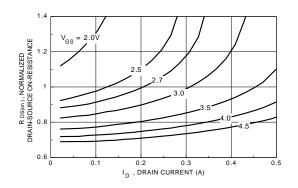


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

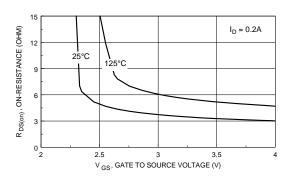


Figure 4. On Resistance Variation with Gate-To-Source Voltage.

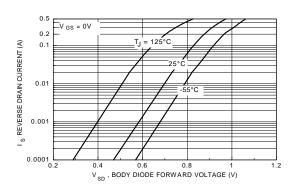


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

# **Typical Electrical And Thermal Characteristics**

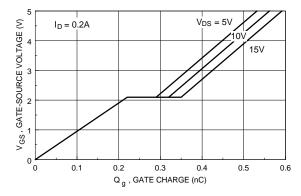


Figure 7. Gate Charge Characteristics.

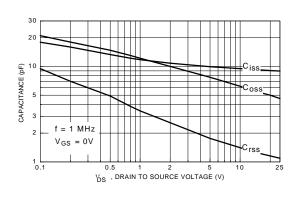


Figure 8. Capacitance Characteristics.

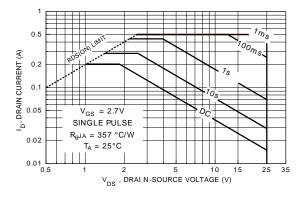


Figure 9. Maximum Safe Operating Area.

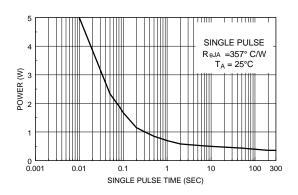


Figure 10. Single Pulse Maximum Power Dissipation.

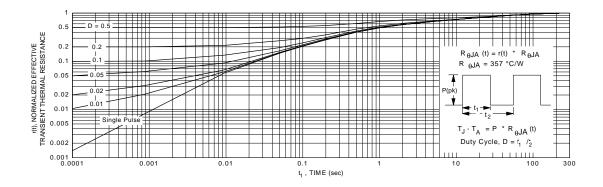


Figure 11. Transient Thermal Response Curve.





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